

DANAE

Status progress

Francesco Cescato
12/11/2025



**Università
degli Studi
di Ferrara**



Status progress - Maintenance of the Dicing machine



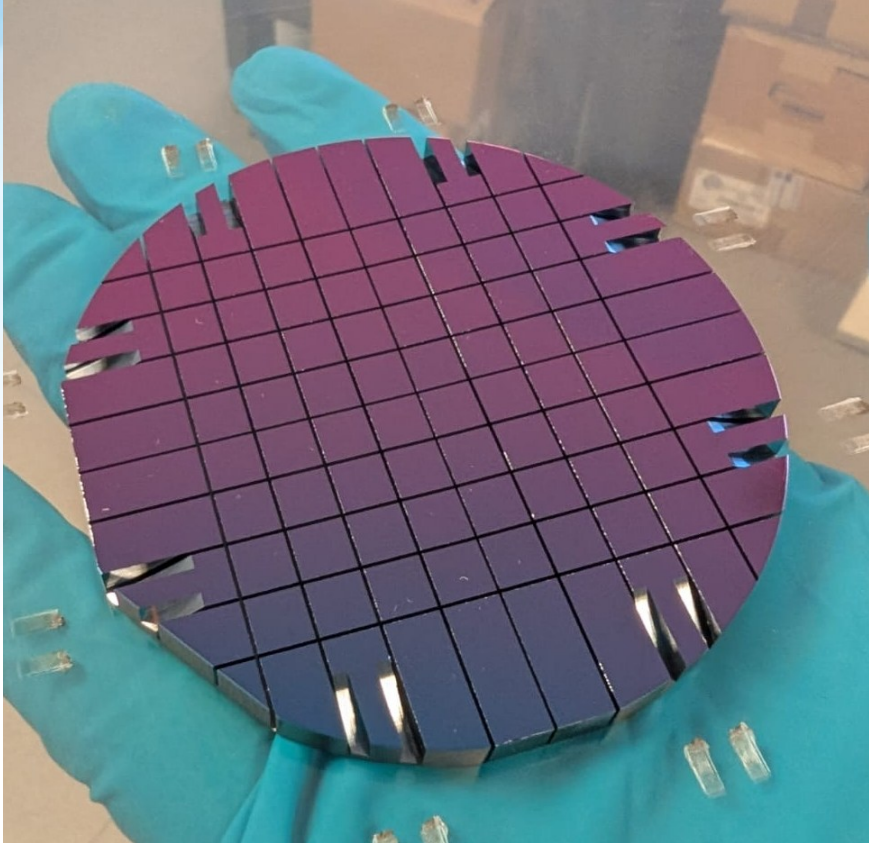
DAD3220 Dicing

The machine showed slowdowns



Maintenance intervention by a technician from the manufacturer

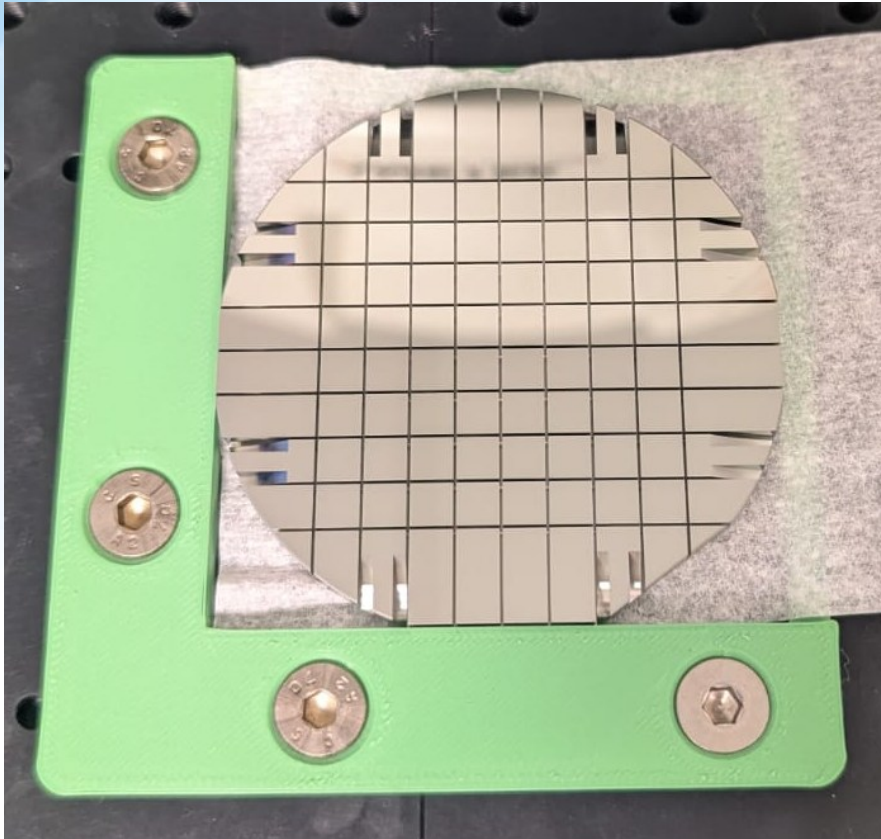
Status progress - Production of 3-inch wafers



**3-inch silicon wafer
with silicon nitride
layer**

- Before the maintenance, we had produced 2 wafers.
- Now we have 5 wafers produced.

Status progress - Production of 3-inch wafers

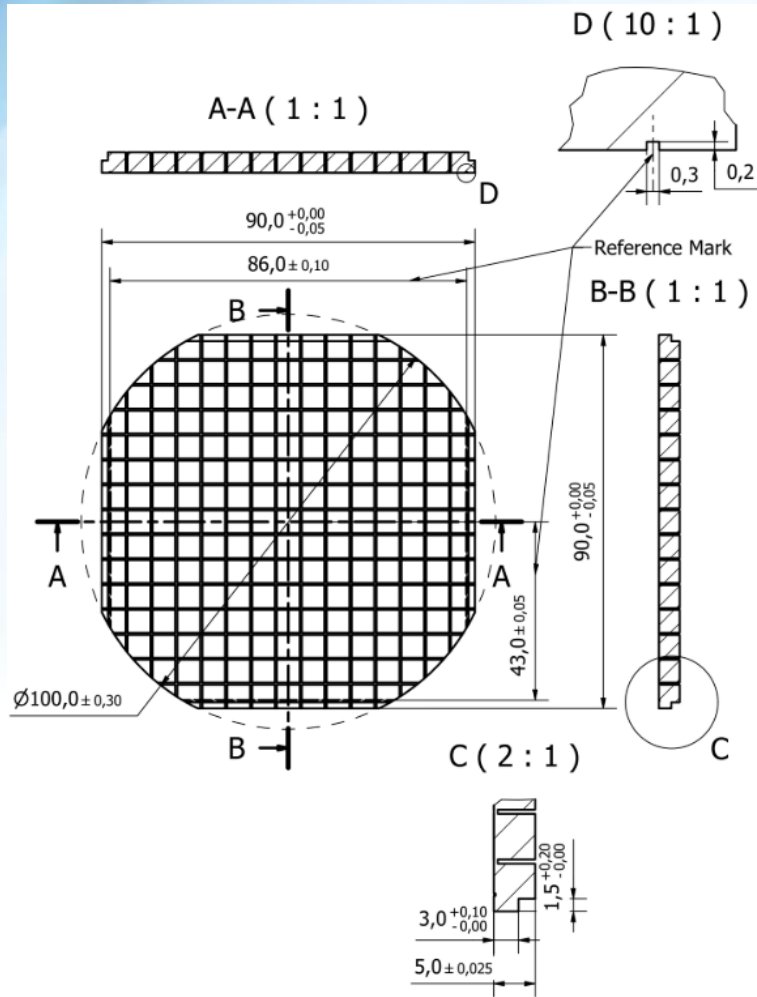


3-inch silicon wafer

Next steps:

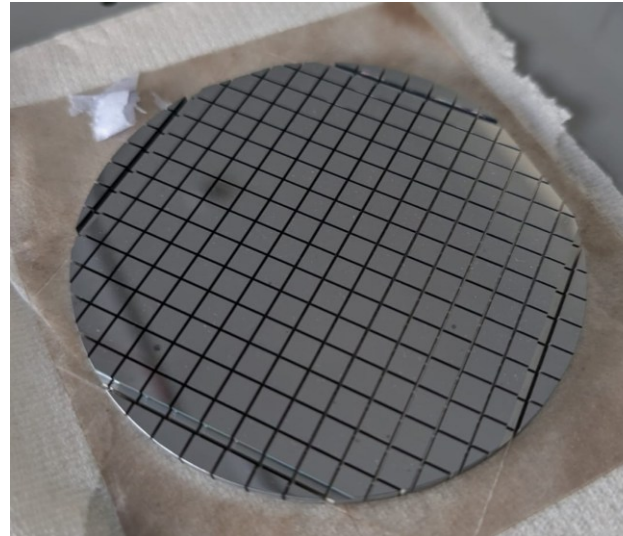
- Characterization of groove depth and width by optical interferometry
- Chemical etching
- Characterization of groove depth and width by optical interferometry after chemical etching
- Nitride removal

Status progress – Production of 4-inch wafers



**4-inch silicon wafer
project**

- We are preparing to process 4-inch wafers



4-inch silicon wafer

Thank you for your attention